

WHAT IS CLAIMED IS:

1. A semiconductor device comprising:  
a plurality of laminated semiconductor elements; and  
5 highly water-absorbing resin films formed between the  
semiconductor elements.
2. The semiconductor device according to claim 1, wherein the highly  
water-absorbing resin films absorb water or a low-boiling-point organic  
10 solvent.
3. The semiconductor device according to claim 1, wherein the highly  
water-absorbing resin films absorb an organic solvent having a boiling  
point equal to or higher than the reflow melting point temperature  
15 of solder.
4. The semiconductor device according to claim 1, further comprising  
heat-dissipating heat sinks installed on the sides of the plurality  
of laminated semiconductor elements.  
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5. A semiconductor device comprising:  
a plurality of laminated semiconductor elements; and  
conductive resin films formed on the whole areas between the  
semiconductor elements.  
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6. A semiconductor device comprising:  
a plurality of laminated semiconductor elements;  
metal plates provided between the semiconductor elements; and  
inner bumps for electrically connecting adjacent semiconductor  
30 elements with each other;

wherein each of the metal plates have openings, whose circumferences have been subjected to insulation treatment, in locations where the inner bumps pass.

- 5    7.    The semiconductor device according to claim 6, further comprising highly water-absorbing resin films formed between the semiconductor elements.